# Radiation Damage in Silicon

Katharina Kaska

#### TA1-SD

Alison Bates, Christian Joram, Michael Moll

## Operation of a detector





Electric field across a new detector

Our test structures  $\overbrace{f}_{5 \text{ mm}}^{\text{SiO}_2}$ 

Radiation creates electron and hole pairs

- -holes are attracted to the p+ electrode
- -electrons are attracted to the n+ electrode

Movement of charge carriers induces a signal.

# Why radiation hard silicon?

#### Example: LHCb VELO (VErtex LOcator) detector:

•8 mm away from the beam (10<sup>14</sup> 1 MeV  $n_{eq}$ )

new detectors needed within ~3 years





# Defects in Silicon

Main (macroscopic) effects of radiation damage in silicon:

- Increased leakage current
- Increased depletion voltage
- Increased trapping

## Types of Silicon

Float Zone (FZ) silicon: 1x10<sup>15</sup> O cm<sup>-3</sup> Oxygenated silicon: 1x10<sup>17</sup> O cm<sup>-3</sup> Czochralski (CZ) silicon: 1x10<sup>18</sup> O cm<sup>-3</sup>



Oxygenated silicon seems to be better than Float Zone silicon. CV and IV measurements

Capacitance [C] and Current [I] vs. Voltage

can be used to determine:

CV

•Full depletion voltage

•End capacitance



- •Full depletion voltage
- Leakage current







W317 (DOFZ) oxygenated

Annealed for 4 min/80°C

Leakage current normalized to volume

 $\alpha = 4.75 \times 10^{-17} \text{A/cm}$ 

Previous works (M. Moll):

 $\alpha = 4.56 \times 10^{-17} \text{ A/cm}$ 

## Transient Current Technique

A technique to study radiation damage in silicon by measuring:

- Full depletion voltage
- Effective trapping time
- Sign of space charge



#### How does TCT work?



t[ns]



3 20 t[ns]

#### OV method Charge vs. Voltage



The QV-method can be used to get the full depletion voltage

$$Q = \int_{t_0}^{t_1} I(t) dt$$

# Effective trapping time

Charge gets trapped in the detector due to radiation induced defects.

The amount of charge trapped depends on the number of defects (hence on the fluence) and also on the applied voltage (over full depletion):

Higher voltage

-> higher drift velocity

-> fewer charge carriers trapped

-> more charge measured

#### How to get the trapping time?

The corrected charge is constant with voltage (V>V<sub>FD</sub>)



#### **b** - values



University	$b_{e} 10^{-16} \text{ cm}^{2}/\text{ns}$	<b>b</b> <sub>h</sub> 10 <sup>-16</sup> cm <sup>2</sup> /ns	Reference
Dortmund	5.16 ± 0.16	5.04 ± 0.16	O. Krasel et al., 2 <sup>nd</sup> RD50 workshop
Ljubljana	5.6 ± 0.2	7.7 ± 0.2	G. Kramberger et al, NI AM A481 (2002) 297-305
Hamburg	4.85 ± 0.15	5.72 ± 0.5	E. Fretwurst et al., 3 <sup>rd</sup> RD50 workshop

# Type inversion



electron signal before type inversion electron signal after type inversion

#### **Results for Cz Silicon**

#### From IV-CV measurements:



TCT can determine the space charge:

(i.e. whether the bulk is still n-type or has changed to p-type)



No type inversion up to 5x10<sup>14</sup> p/cm<sup>2</sup> in CZ silicon

### Conclusions

•Float Zone and Oxygenated silicon type invert

•The QV method is complementary to CV and IV to determine the depletion voltage

•Preliminary  $\beta$ -values for electrons agree with previous results, holes agree with Hamburg group (for W317)

•Czochralski silicon doesn't type invert up to 5x10<sup>14</sup> p/cm2

#### QUESTIONS?????

### Irradiation and annealing

The samples are irradiated with a fluence between  $10^{12} - 10^{15} \text{ p/cm}^{-2}$  (24 GeV protons) at I RRAD1 (PS).

Before measurements the detectors are annealed to remove movable carriers and get them all on the same damage level.

## TCT Setup





## How to get the trapping time?

Due to trapping the current measured is lower than the actual current  $I_0$ :

$$I(t) = I_0(t)e^{-\frac{t}{t}}$$

From this relation follows for the charge

$$Q(t) = \int I_0(t)dt = \int I(t)e^{-\frac{t}{t}}dt$$